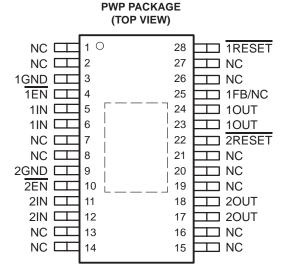
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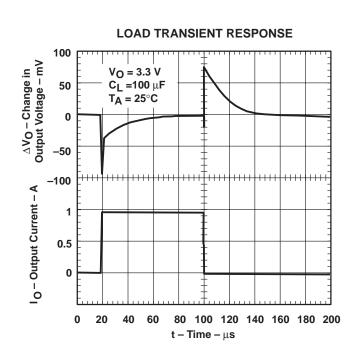
- Output Current Range of 0 mA to 1.0 A Per Regulator
- 3.3-V/2.5-V, 3.3-V/1.8-V, and 3.3-V/Adjustable Output
- **Fast-Transient Response**
- 2% Tolerance Over Load and Temperature
- Dropout Voltage Typically 350 mV at 1 A
- **Ultra Low 85 μA Typical Quiescent Current**
- 1 μA Quiescent Current During Shutdown
- **Dual Open Drain Power-On Reset With** 200-ms Delay for Each Regulator
- 28-Pin PowerPAD™ TSSOP Package
- **Thermal Shutdown Protection for Each** Regulator

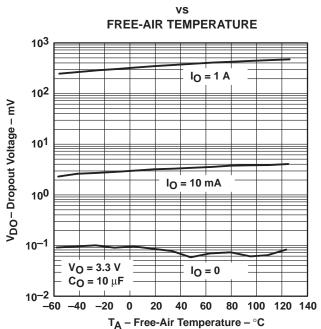


NC - No internal connection

description

The TPS767D3xx family of dual voltage regulators offers fast transient response, low dropout voltages and dual outputs in a compact package and incorporating stability with 10-μF low ESR output capacitors.





DROPOUT VOLTAGE



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PowerPAD is a trademark of Texas Instruments Incorporated.

description (continued)

The TPS767D3xx family of dual voltage regulators is designed primarily for DSP applications. These devices can be used in any mixed-output voltage application, with each regulator supporting up to 1 A. Dual active-low reset signals allow resetting of core-logic and I/O separately.

Because the PMOS device behaves as a low-value resistor, the dropout voltage is very low (typically 350 mV at an output current of 1 A for the TPS767D325) and is directly proportional to the output current. Additionally, since the PMOS pass element is a voltage-driven device, the quiescent current is very low and independent of output loading (typically 85 μ A over the full range of output current, 0 mA to 1 A). These two key specifications yield a significant improvement in operating life for battery-powered systems. This LDO family also features a sleep mode; applying a TTL high signal to $\overline{\text{EN}}$ (enable) shuts down the regulator, reducing the quiescent current to 1 μ A at $T_{\text{LI}} = 25^{\circ}\text{C}$.

The RESET output of the TPS767D3xx initiates a reset in microcomputer and microprocessor systems in the event of an undervoltage condition. An internal comparator in the TPS767D3xx monitors the output voltage of the regulator to detect an undervoltage condition on the regulated output voltage.

The TPS767D3xx is offered in 1.8-V, 2.5-V, and 3.3-V fixed-voltage versions and in an adjustable version (programmable over the range of 1.5 V to 5.5 V). Output voltage tolerance is specified as a maximum of 2% over line, load, and temperature ranges. The TPS767D3xx family is available in 28 pin PWP TSSOP package. They operate over a junction temperature range of -40° C to 125° C.

AVAILABLE OPTIONS

| TA | REGULATOR 1 V _O (V) | REGULATOR 2 V _O (V) | TSSOP (PWP) |
|----------------|-----------------------------------|-----------------------------------|----------------|
| | Adj (1.5 – 5.5 V) | 3.3 V | TPS767D301PWP |
| -40°C to 125°C | 1.8 V | 3.3 V | TPS767D318PWP |
| | 2.5 V | 3.3 V | TPS767D325PWP |

The TPS767D301 is adjustable using an external resistor divider (see application information). The PWP packages are available taped and reeled. Add an R suffix to the device type (e.g., TPS767D301PWPR).

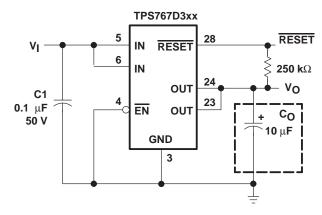
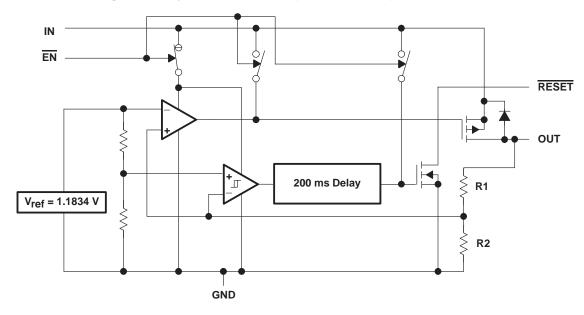


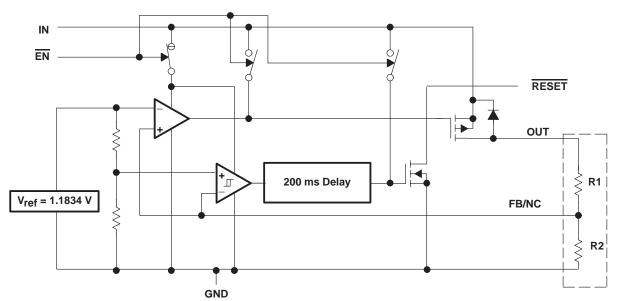
Figure 1. Typical Application Circuit (Fixed Versions) for Single Channel



functional block diagram—adjustable version (for each LDO)



functional block diagram—fixed-voltage version (for each LDO)



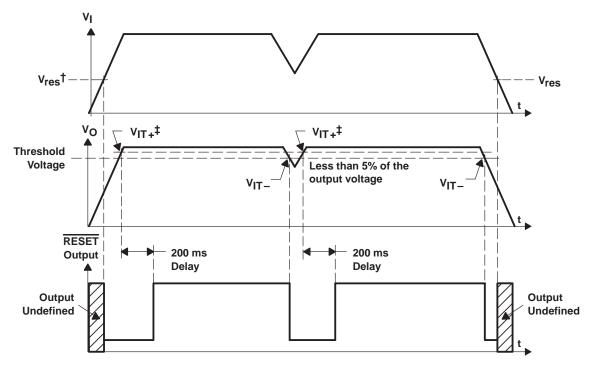
External to the device

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Terminal Functions

| TE | RMINAL | 1/0 | DESCRIPTION | | | |
|--------|---|-----|---|--|--|--|
| NAME | NO. | 1/0 | DESCRIPTION | | | |
| 1GND | 3 | | Regulator #1 ground | | | |
| 1EN | 4 | 1 | Regulator #1 enable | | | |
| 1IN | 5, 6 | 1 | Regulator #1 input supply voltage | | | |
| 2GND | 9 | | Regulator #2 ground | | | |
| 2EN | 10 | - 1 | Regulator #2 enable | | | |
| 2IN | 11, 12 | I | Regulator #2 input supply voltage | | | |
| 2OUT | 17, 18 | 0 | Regulator #2 output voltage | | | |
| 2RESET | 22 | 0 | Regulator #2 reset signal | | | |
| 1OUT | 23, 24 | 0 | Regulator #1 output voltage | | | |
| 1FB/NC | 25 | 1 | Regulator #1 output voltage feedback for adjustable and no connect for fixed output | | | |
| 1RESET | 28 | 0 | Regulator #1 reset signal | | | |
| NC | 1, 2, 7, 8, 13–16, 19, 20, 21, 26, 27 | | No connection | | | |

timing diagram



 $[\]dagger$ V_{res} is the minimum input voltage for a valid $\overline{\text{RESET}}$. The symbol V_{res} is not currently listed within EIA or JEDEC standards for semiconductor symbology.



 $[\]ddagger$ VIT –Trip voltage is typically 5% lower than the output voltage (95% V_O)

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

| Input voltage range [‡] , V _I | 0.3 V to 13.5 V |
|--|--|
| Input voltage range, V _I (1IN, 2IN, EN) | $-0.3 \text{ V to V}_{\text{I}} + 0.3 \text{ V}$ |
| Output voltage, VO (10UT, 20UT) | 7 V |
| Output voltage, VO (RESET) | 16.5 V |
| Peak output current | Internally limited |
| ESD rating, HBM | 2 kV |
| Continuous total power dissipation | See dissipation rating tables |
| Operating virtual junction temperature range, T _J | –40°C to 125°C |
| Storage temperature range, T _{stq} | 65°C to 150°C |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

DISSIPATION RATING TABLE

| | PACKAGE | AIR FLOW (CFM) | $T_A \le 25^{\circ}C$ POWER RATING | DERATING FACTOR ABOVE T _A = 25°C | T _A = 70°C POWER RATING | T _A = 85°C POWER RATING |
|---|---------|-------------------|------------------------------------|--|---------------------------------------|---------------------------------------|
| Γ | DIAKE+ | 0 | 3.58 W | 35.8 mW/°C | 1.97 W | 1.43 W |
| 1 | PWPT | 250 | 5.07 W | 50.7 mW/°C | 2.79 W | 2.03 W |

[†] This parameter is measured with the recommended copper heat sink pattern on a 4–layer PCB, 1 oz. copper on 4–in x 4–in ground layer. For more information, refer to TI technical brief literature number SLMA002.

recommended operating conditions

| | MIN | MAX | UNIT |
|--|-----|-----|------|
| Input voltage, V _I # (1IN, 2IN) | 2.7 | 10 | V |
| Output current for each LDO, IO (Note 1) | 0 | 1.0 | Α |
| Output voltage range, VO (10UT, 20UT) | 1.5 | 5.5 | V |
| Operating virtual junction temperature, T _J | -40 | 125 | °C |

[#] To calculate the minimum input voltage for your maximum output current, use the following equation: V_{I(min)} = V_{O(max)} + V_{DO(max load)}.

NOTE 1: Continuous current and operating junction temperature are limited by internal protection circuitry, but it is not recommended that the device operate under conditions beyond those specified in this table for extended periods of time.



[‡] All voltage values are with respect to network terminal ground.

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electrical characteristics, $V_i = V_{O(nom)} + 1 V$, $I_O = 1 \text{ mA}$, $\overline{EN} = 0$, $C_O = 10 \,\mu\text{F} (\text{unless otherwise noted})$

| PARAMETER | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT |
|--|------------------------|---|---|--------------------|------|--------------------|-------|
| | Adjustable | $1.5 \text{ V} \le \text{V}_{\text{O}} \le 5.5 \text{ V},$ | T _J = 25°C | | ٧o | | v |
| | rajustable | 10 μA < I _O < 1 A | $T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$ | 0.98V _O | | 1.02V _O | |
| | 1.8 V Ouput | 2.8 V < V _I < 10 V, | T _J = 25°C | | 1.8 | | |
| Output voltage (VO) | 1.0 v Ouput | 10 μA < I _O < 1 A | $T_{J} = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$ | 1.764 | | 1.836 | |
| (see Note 2) | 2.5 V Output | 3.5 V < V _I < 10 V, | T _J = 25°C | | 2.5 | | |
| ļ | 2.5 v Output | 10 μA < I _O < 1 A | $T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$ | 2.45 | | 2.55 | |
| ļ | 3.3 V Output | 4.3 V < V _I < 10 V, | T _J = 25°C | | 3.3 | | V |
| | | 10 μA < I _O < 1 A | $T_J = -40^{\circ}C \text{ to } 125^{\circ}C$ | 3.234 | | 3.366 | _ |
| Quiescent current (GND current) for ea | ach LDO | 10 μA < I _O < 1 A, | T _J = 25°C | | 85 | | μΑ |
| (see Note 2) | | I _O = 1 A, | $T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$ | | | 125 | μΑ |
| Output voltage line regulation for each LDO ($\Delta V_O/V_O$) (see Notes 2 and 3) | | $V_{O} + 1 V < V_{I} \le 10 V$, | T _J = 25°C | | 0.01 | | %/V |
| Output noise voltage | | BW = 300 Hz to 50 kHz $C_O = 10 \mu F$, | z, T _J = 25°C | | 190 | | μVrms |
| Output current Limit for each LDO | | V _O = 0 V | | | 1.7 | 2 | Α |
| Thermal shutdown juction temperature | | | | | 150 | | °C |
| | | $2.7 < V_I < 10V$, $T_J = 25^{\circ}C$, | $\overline{EN} = V_{I},$ | | 1 | | μΑ |
| Standby current for each LDO | | $2.7 < V_I < 10V$, $T_J = -40^{\circ}C$ to $125^{\circ}C$ | EN = V _I , | | | 10 | μΑ |
| FB input current | Adjustable | FB = 1.5 V | | | 2 | | nA |
| High level enable input voltage | | | | 2.0 | | | V |
| Low level enable input voltage | | | | | | 8.0 | V |
| Power supply ripple rejection (see Note 2) | | f = 1 KHz, T _J = 25°C, | $C_{O} = 10 \mu F$ | | 60 | | dB |
| Minimum input voltage for valid RESET | | I _O (RESET) = 300μA | | | 1.1 | | V |
| Trip threshold voltage | Trip threshold voltage | | | 92 | | 98 | %Vo |
| Reset Hysteresis voltage | Hysteresis voltage | | | | 0.5 | | %Vo |
| Output low voltage | | V _I = 2.7 V, | IO(RESET) = 1 mA | | 0.15 | 0.4 | V |
| Leakage current | | V(RESET) = 7 V | · | | | 1 | μА |
| RESET time-out delay | | | | | 200 | | mA |

NOTES: 2. Minimum IN operating voltage is 2.7 V or V_{O(typ)} + 1 V, whichever is greater. maximum IN voltage 10V. 3. If VO ≤ 1.8 V, V_{imin} = 2.7 V, and V_{imax} = 10 V:

Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{imax} - 2.7 \text{ V})}{100} \times 1000$$

If VO \geq 2.5 V, V_{imin} = Vo + 1 V, and V_{imax} = 10 V:

Line Reg. (mV) =
$$(\%/V) \times \frac{V_O(V_{imax} - (V_O + 1 V))}{100} \times 1000$$

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electrical characteristics, $V_i = V_{O(nom)} + 1 V$, $I_O = 1 \text{ mA}$, $\overline{EN} = 0$, $C_O = 10 \,\mu\text{F(unless otherwise noted)}$ (continued)

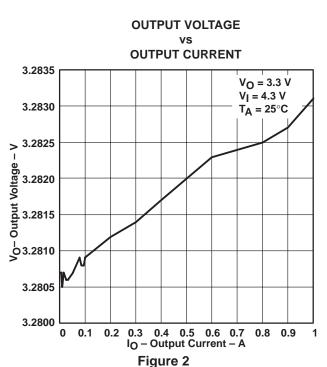
| PARAMETER | TEST CONDITIONS | | | TYP | MAX | UNIT |
|------------------------------|-------------------------|---|----|-----|-----|------|
| Input ourrent (ENI) | EN = 0 V | | -1 | 0 | 1 | μΑ |
| Input current (EN) | EN = V _I | | -1 | | 1 | |
| Load regulation | | | | 3 | | mV |
| Dropout voltage (and Note 4) | V _O = 3.3 V, | T _J = 25°C | | 350 | | mV |
| Dropout voltage (see Note 4) | I _O = 1 A | $T_J = -40^{\circ}\text{C} \text{ to } 125^{\circ}\text{C}$ | | | 575 | IIIV |

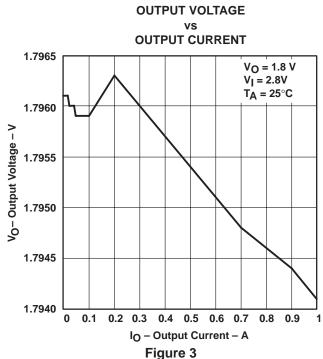
NOTE 4: IN voltage equals Vo(Typ) – 100mV; Adjustable output voltage set to 3.3V nominal with external resistor divider. 1.8V, and 2.5V dropout voltage is limited by input voltage range limitations.

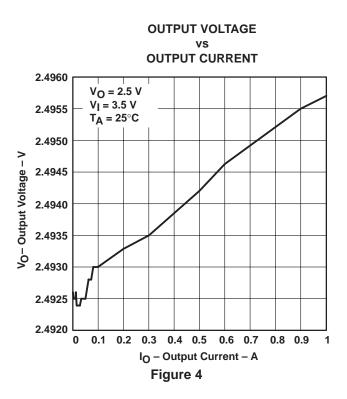
TYPICAL CHARACTERISTICS

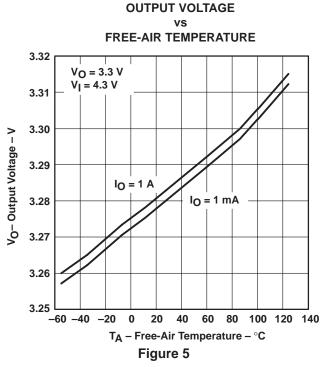
Table of Graphs

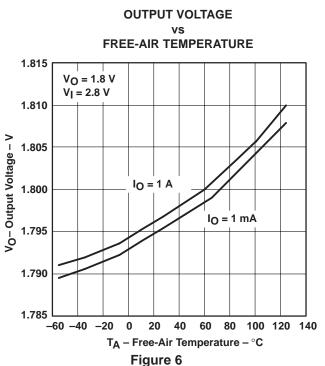
| | | FIGURE |
|--|---|---------|
| Custous valtage | vs Output current | 2, 3, 4 |
| Output voltage | vs Free-air temperature | 5, 6, 7 |
| Ground current | vs Free-air temperature | 8, 9 |
| Power supply ripple rejection | vs Frequency | 10 |
| Output spectral noise density | vs Frequency | 11 |
| Output impedance | vs Frequency | 12 |
| Dropout voltage | vs Free-air temperature | 13 |
| Line transient response | | 14, 16 |
| Load transient response | | 15, 17 |
| Output voltage | vs Time | 18 |
| Dropout voltage | vs Input voltage | 19 |
| | vs Output current, T _A = 25°C | 21 |
| Facility along the project of the Control of the Co | vs Output current, T _J = 125°C | 22 |
| Equivalent series resistance (ESR) | vs Output Current, T _A = 25°C | 23 |
| | vs Output current, T _J = 125°C | 24 |

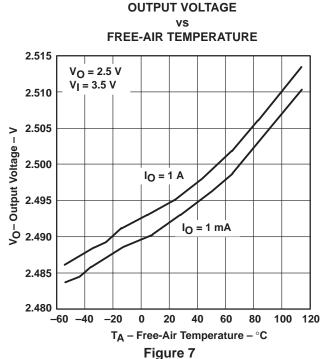


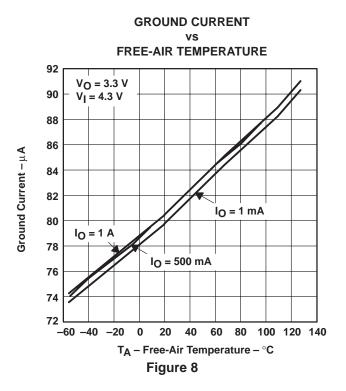


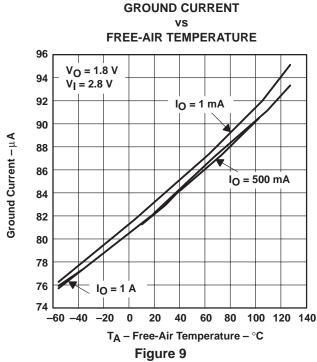


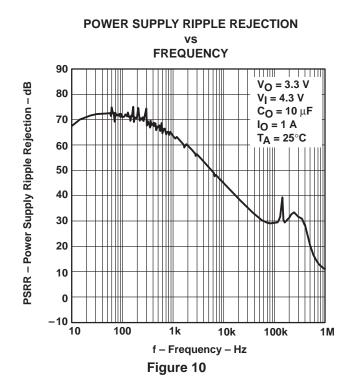


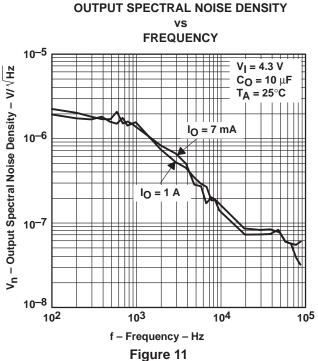


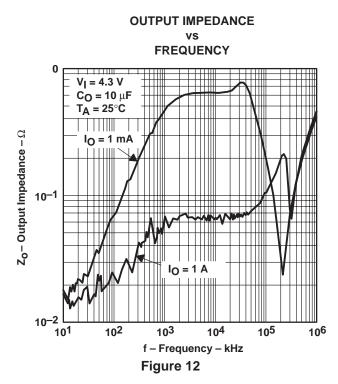


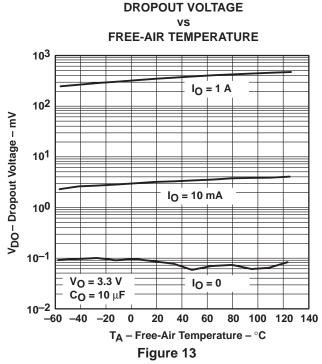


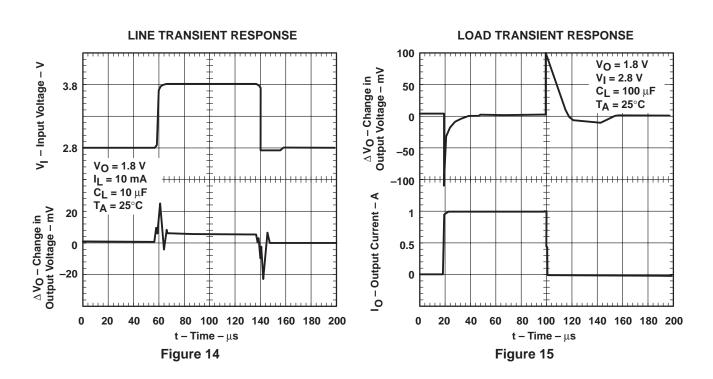


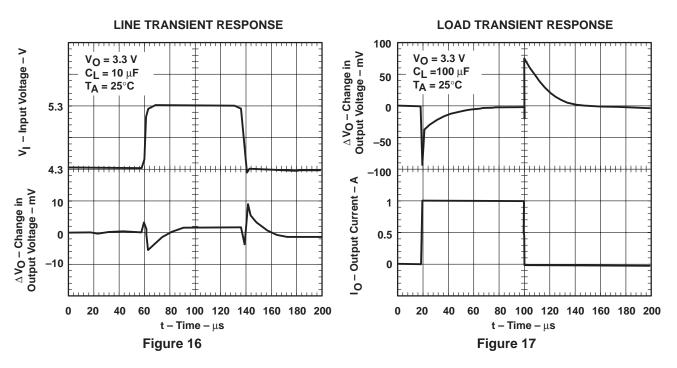












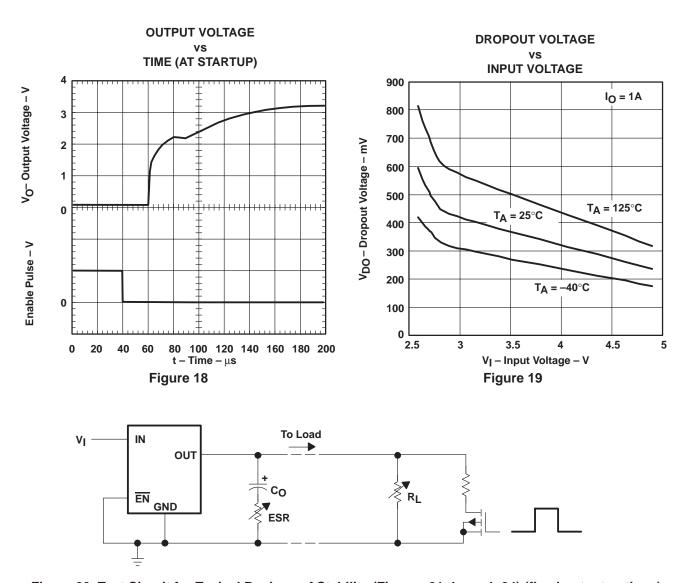


Figure 20. Test Circuit for Typical Regions of Stability (Figures 21 through 24) (fixed output options)

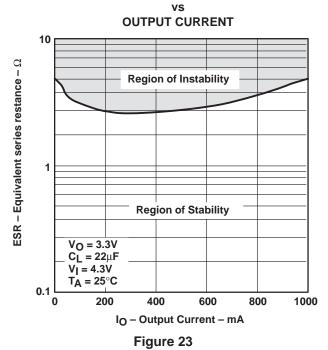
EQUIVALENT SERIES RESISTANCE[†] vs **OUTPUT CURRENT** 10 ESR – Equivalent series restance – Ω Region of Instability 1 Region of Stability $V_0 = 3.3V$ $C_L = 4.7 \mu F$ $V_{I} = 4.3V$ T_A = 25°C 0. 200 0 400 600 800 1000

TYPICAL REGION OF STABILITY

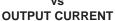
Figure 21

TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE[†]

IO - Output Current - mA



TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE[†] vs



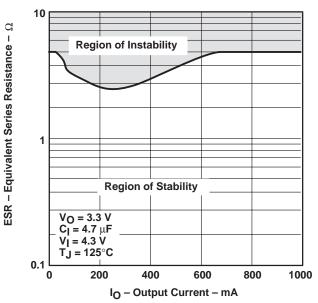
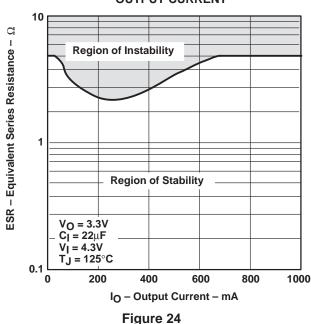


Figure 22

TYPICAL REGION OF STABILITY EQUIVALENT SERIES RESISTANCE[†]

vs OUTPUT CURRENT



[†] Equivalent series resistance (ESR) refers to the total series resistance, including the ESR of the capacitor, any series resistance added externally, and PWB trace resistance to Co.



APPLICATION INFORMATION

The features of the TPS767D3xx family (low-dropout voltage, ultra low quiescent current, power-saving shutdown mode, and a supply-voltage supervisor) and the power-dissipation properties of the TSSOP PowerPAD package have enabled the integration of the dual LDO regulator with high output current for use in DSP and other multiple voltage applications. Figure 25 shows a typical dual-voltage DSP application.

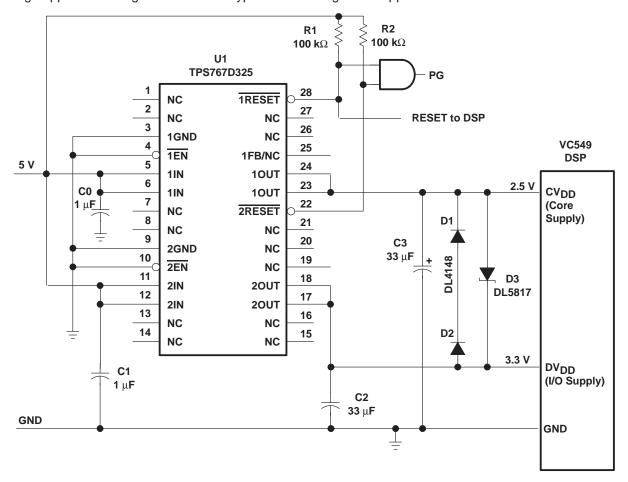


Figure 25. Dual-Voltage DSP Application

DSP power requirements include very high transient currents that must be considered in the initial design. This design uses higher-valued output capacitors to handle the large transient currents.

device operation

The TPS767D3xx features very low quiescent current, which remain virtually constant even with varying loads. Conventional LDO regulators use a pnp pass element, the base current of which is directly proportional to the load current through the regulator ($I_B = I_C/\beta$). Close examination of the data sheets reveals that these devices are typically specified under near no-load conditions; actual operating currents are much higher as evidenced by typical quiescent current versus load current curves. The TPS767D3xx uses a PMOS transistor to pass current; because the gate of the PMOS is voltage driven, operating current is low and invariable over the full load range. The TPS767D3xx specifications reflect actual performance under load condition.



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Another pitfall associated with the pnp-pass element is its tendency to saturate when the device goes into dropout. The resulting drop in β forces an increase in I_B to maintain the load. During power up, this translates to large start-up currents. Systems with limited supply current may fail to start up. In battery-powered systems, it means rapid battery discharge when the voltage decays below the minimum required for regulation. The TPS767D3xx guiescent current remains low even when the regulator drops out, eliminating both problems.

The TPS767D3xx family also features a shutdown mode that places the output in the high-impedance state (essentially equal to the feedback-divider resistance) and reduces quiescent current to under 2 μ A. If the shutdown feature is not used, $\overline{\text{EN}}$ should be tied to ground. Response to an enable transition is quick; regulated output voltage is typically reestablished in 120 μ s.

minimum load requirements

The TPS767D3xx family is stable even at zero load; no minimum load is required for operation.

FB - pin connection (adjustable version only)

The FB pin is an input pin to sense the output voltage and close the loop for the adjustable option. The output voltage is sensed through a resistor divider network as is shown in Figure 27 to close the loop. Normally, this connection should be as short as possible; however, the connection can be made near a critical circuit to improve performance at that point. Internally, FB connects to a high-impedance wide-bandwidth amplifier and noise pickup feeds through to the regulator output. Routing the FB connection to minimize/avoid noise pickup is essential. In fixed output options this pin is a no connect.

external capacitor requirements

An input capacitor is not required; however, a ceramic bypass capacitor (0.047 pF to 0.1 μ F) improves load transient response and noise rejection when the TPS767D3xx is located more than a few inches from the power supply. A higher-capacitance electrolytic capacitor may be necessary if large (hundreds of milliamps) load transients with fast rise times are anticipated.

Like all low dropout regulators, the TPS767D3xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 10 μ F and the ESR (equivalent series resistance) must be between 50 m Ω and 1.5 Ω . Capacitor values 10 μ F or larger are acceptable, provided the ESR is less than 1.5 Ω . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described previously.



external capacitor requirements (continued)

When necessary to achieve low height requirements along with high output current and/or high ceramic load capacitance, several higher ESR capacitors can be used in parallel to meet the previous guidelines.

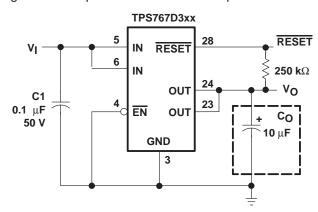


Figure 26. Typical Application Circuit (Fixed Versions) for Single Channel

programming the TPS767D301 adjustable LDO regulator

The output voltage of the TPS767D301 adjustable regulator is programmed using an external resistor divider as shown in Figure 27. The output voltage is calculated using:

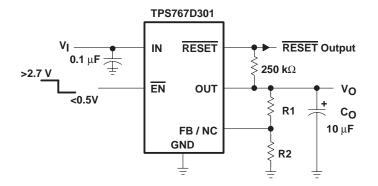
$$V_{O} = V_{ref} \times \left(1 + \frac{R1}{R2}\right) \tag{1}$$

Where:

V_{ref} = 1.1834 V typ (the internal reference voltage)

Resistors R1 and R2 should be chosen for approximately 50- μ A divider current. Lower value resistors can be used but offer no inherent advantage and waste more power. Higher values should be avoided as leakage currents at FB increase the output voltage error. The recommended design procedure is to choose R2 = 30.1 k Ω to set the divider current at 50 μ A and then calculate R1 using:

$$R1 = \left(\frac{V_{O}}{V_{ref}} - 1\right) \times R2 \tag{2}$$



OUTPUT VOLTAGE PROGRAMMING GUIDE

| OUTPUT VOLTAGE | R1 | R2 | UNIT |
|-------------------|------|------|------|
| 2.5 V | 33.2 | 30.1 | kΩ |
| 3.3 V | 53.6 | 30.1 | kΩ |
| 3.6 V | 61.9 | 30.1 | kΩ |
| 4 75V | 90.8 | 30.1 | kΩ |

Figure 27. TPS767D301 Adjustable LDO Regulator Programming



Reset indicator

The TPS767D3xx features a RESET output that can be used to monitor the status of the regulator. The internal comparator monitors the output voltage: when the output drops to 95% (typical) of its regulated value, the RESET output transistor turns on, taking the signal low. The open-drain output requires a pullup resistor. If not used, it can be left floating. RESET can be used to drive power-on reset circuitry or as a low-battery indicator.

regulator protection

The TPS767D3xx PMOS-pass transistor has a built-in back-gate diode that safely conducts reverse currents when the input voltage drops below the output voltage (e.g., during power down). Current is conducted from the output to the input and is not internally limited. When extended reverse voltage is anticipated, external limiting may be appropriate.

The TPS767D3xx also features internal current limiting and thermal protection. During normal operation, the TPS767D3xx limits output current to approximately 1.7 A. When current limiting engages, the output voltage scales back linearly until the overcurrent condition ends. While current limiting is designed to prevent gross device failure, care should be taken not to exceed the power dissipation ratings of the package. If the temperature of the device exceeds 150°C(typ), thermal-protection circuitry shuts it down. Once the device has cooled below 130°C(typ), regulator operation resumes.

power dissipation and junction temperature

Specified regulator operation is assured to a junction temperature of 125° C; the maximum junction temperature should be restricted to 125° C under normal operating conditions. This restriction limits the power dissipation the regulator can handle in any given application. To ensure the junction temperature is within acceptable limits, calculate the maximum allowable dissipation, $P_{D(max)}$, and the actual dissipation, P_{D} , which must be less than or equal to $P_{D(max)}$.

The maximum-power-dissipation limit is determined using the following equation:

$$P_{D(max)} = \frac{T_J max - T_A}{R_{\theta JA}}$$

Where:

T_.Imax is the maximum allowable junction temperature

 $R_{\theta JA}$ is the thermal resistance junction-to-ambient for the package, i.e., 27.9°C/W for the 28-terminal PWP with no airflow.

 T_A is the ambient temperature.

The regulator dissipation is calculated using:

$$P_D = (V_I - V_O) \times I_O$$

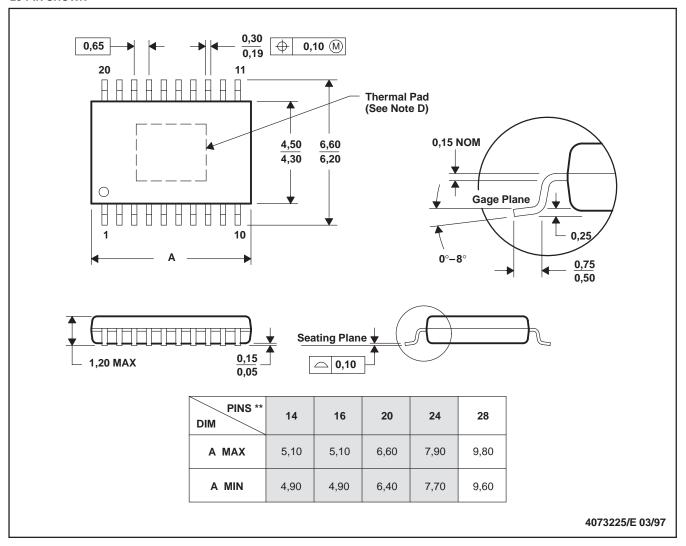
Power dissipation resulting from quiescent current is negligible. Excessive power dissipation will trigger the thermal protection circuit.

MECHANICAL DATA

PWP (R-PDSO-G**)

PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE

20-PIN SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusions.
- D. The package thermal performance may be enhanced by bonding the thermal pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
- E. Falls within JEDEC MO-153

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